



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



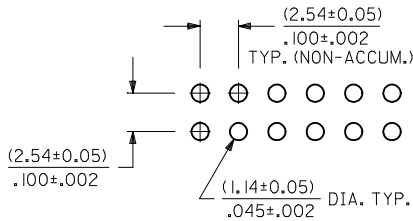
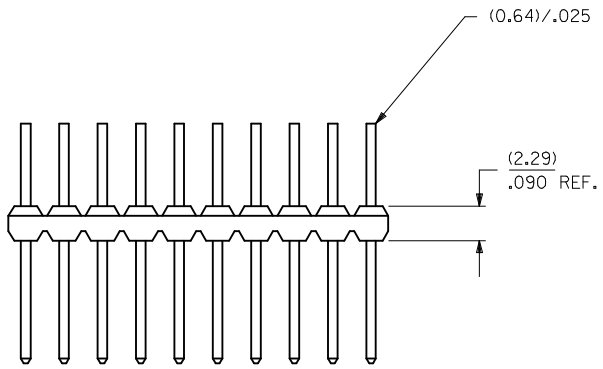
Contact us

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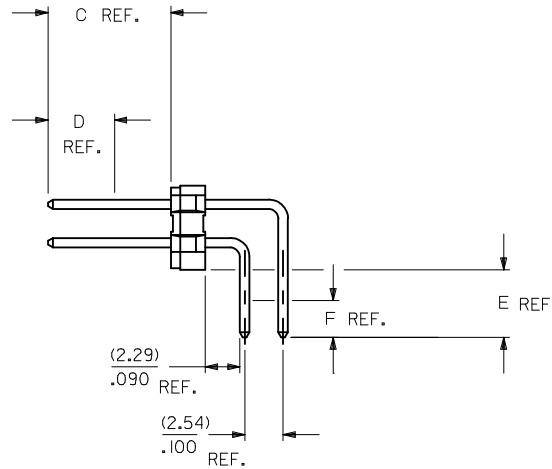
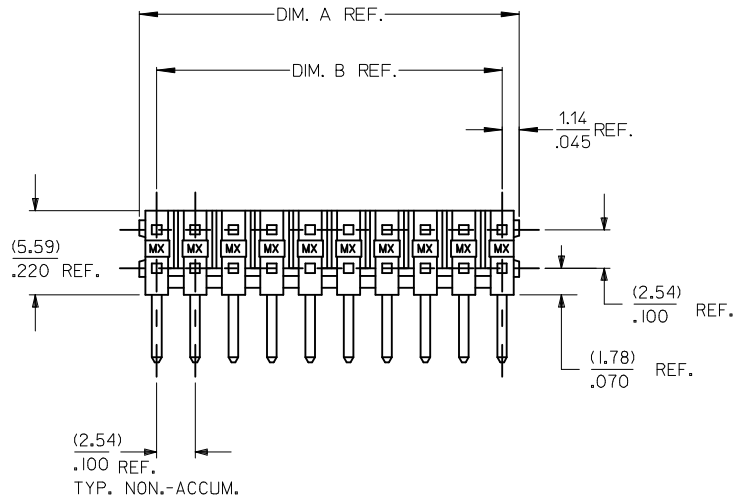
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





RECOMMENDED P.C. BOARD HOLE LAYOUT

CKT. SIZE	DIM. A		DIM. B	
	MM	INCH	MM	INCH
04	4.83	.190	2.54	.100
06	7.37	.290	5.08	.200
08	9.91	.390	7.62	.300
10	12.45	.490	10.16	.400
12	14.99	.590	12.70	.500
14	17.53	.690	15.24	.600
16	20.07	.790	17.78	.700
18	22.61	.890	20.32	.800
20	25.15	.990	22.86	.900
22	27.69	1.090	25.40	1.000
24	30.23	1.190	27.94	1.100
26	32.77	1.290	30.48	1.200
28	35.31	1.390	33.02	1.300
30	37.85	1.490	35.56	1.400



NOTES:

1. MATERIAL: WAFER - GLASS-FILLED POLYESTER, 94V-0; COLOR: BLACK.
PINS - COPPER ALLOY
2. FINISH:
TIN - 0.00381/0.000150 MINIMUM TIN OVER 0.00127/0.000050 MINIMUM NICKEL OVERALL.
15 GOLD - 0.00038/0.000015 MINIMUM GOLD PLATE IN SELECTED AREA AND 0.00191/0.000075 MINIMUM TIN IN SELECTED AREA OVER 0.00127/0.000050 MINIMUM NICKEL OVERALL.
30 GOLD - 0.00076/0.000030 MINIMUM GOLD PLATE IN SELECTED AREA AND 0.00191/0.000075 MINIMUM TIN IN SELECTED AREA OVER 0.00121/0.000050 MINIMUM NICKEL OVERALL.
3. PRODUCT SPECIFICATION: PS-70216.
4. PACKAGING SPECIFICATION: FOR 4 THROUGH 8 CIRCUIT PARTS, SEE PK-70873-0353.
FOR 10 CIRCUITS AND OVER, SEE PK-70873-0075.
5. PIN PUSHOUT FORCE: 3 LBS. MINIMUM.
6. FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE WAFER IS SHOWN.
7. PINS MUST MEET SOLDERABILITY SPEC. SMES-152.
8. WAFER TO BE FLAT WITHIN (0.03 MM/CM) OR .003 IN./IN.
9. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

REV	DESCRIPTION	DATE	APPROVED BY
1	PIN PUSHOUT FORCE	2013/07/17	DRW:MKL/PPR
2		2013/07/17	CHKD:ANDERSON
3		2013/09/17	APPR:FSM/TH

QUALITY SYMBOLS		GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH	mm	INCH
4 PLACES ± ---	± ---	± 0.13	± .01
3 PLACES ± ---	± .005	± 0.25	± ---
2 PLACES ± 0.13	± .01	±	±
1 PLACE ± 0.25	± ---	ANGULAR ±1/2°	
0 PLACE ±	±	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE		SCALE	DESIGN UNITS
MM/IN		4:1	INCH
DRAWN BY	DATE	TITLE	
RCB	1994/05/18	RT. ANG. WAFER ASS'Y	
CHECKED BY	DATE	2.54/.100 GRID, DUAL ROW	
RCB	1994/05/18	BREAKAWAY 0.64/.025 PINS	
APPROVED BY	DATE	molex	
SMILLER	2010/10/06	DOCUMENT NO. SD-70216-001	
MATERIAL NO.		SHEET NO. 1 OF *	
SEE CHART			

THIRD ANGLE PROJECTION	
2-*	A1
1	C
SHT. REV	